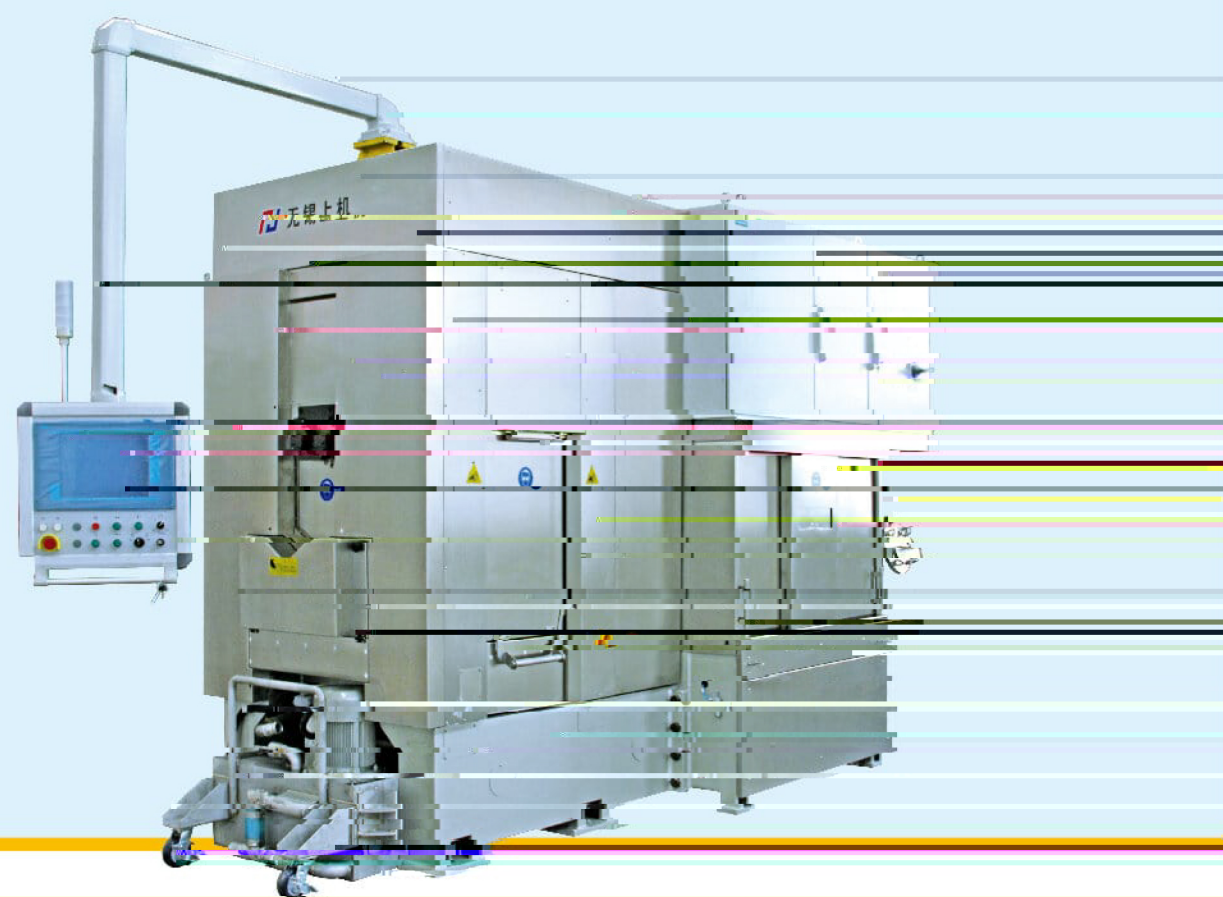


WSK060

蓝宝石切片机

WSK060 Sapphire Slicing Machine



技术规格参数 Specifications and Technical Parameters

规格 Specification	6 inches (max)
长度 Length	800mm
厚度 Thickness	>0.2mm

主要参数 Main Parameters

导轮直径 Guide wheel diameter	220mm
导轮轴距 Guide wheel base	440mm
导轮长度 Guide wheel length	366mm
线速度 Wire speed	5000mm/min
进给速率 Feed rate	0.1mm, 200mm/min
摇摆角度 Swinging angle	±12°
切割方向 Cutting direction	前进或后退切割/双向切割 forward or reverse cutting
存储线圈 Storage wire wheels	>200km
切割容量 Wire capacity	3200L

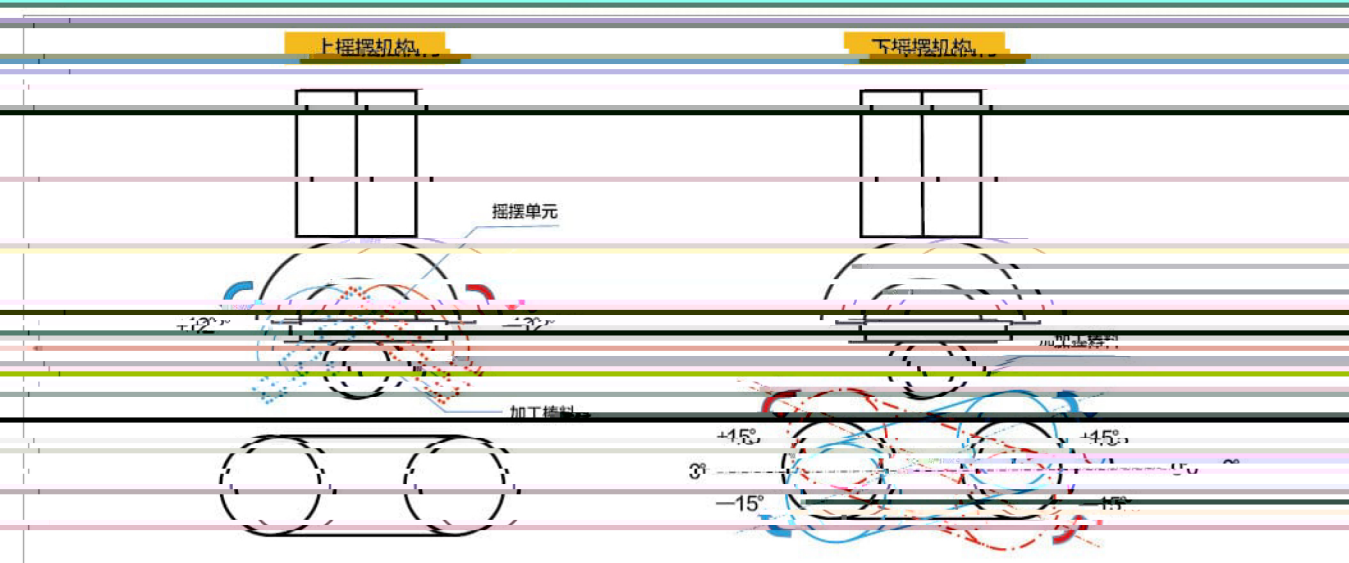
能源供应 Power supply

电源电压 Power supply voltage	220V/380V, 50Hz, 3000V
平均功率 Average power	35KW
冷却水温 Cooling water temperature	12~17℃

外形尺寸 Outline size

机床外形尺寸 (长*宽*高) Equipment size (L*W*H)	1600*2100*2200mm
机床重量 weight	≈ 12000kg

示意图 Sketch



设备用途与性能特征

- 本机床用于自动切割长条、坚硬、易脆材料，如硅、锗、石英玻璃、陶瓷、蓝宝石晶体等。
- 机床所有电器元件均采用国际国内知名品牌，保证机床的稳定性。
- 采用西门子的控制技术的 一体化PC机，15"触摸屏。
- 电控柜配备独立温控系统，保证各控制元件正常工作。
- 设备具备摇摆功能，双支撑摇摆单元优化了金刚线切割蓝宝石的性能，缩短了切割时间，并提高了晶片的质量。
- 滑轮数量最少化设计（仅6个滑轮），减少刚线扭曲和疲劳。

Application and Features

- The machine is used for automatic cutting of long, hard, and brittle materials, using diamond tools to cut silicon, germanium, quartz glass, ceramics, sapphire crystals, etc.
- All electrical components apply international and domestic outstanding brands to ensure the stability of the machine.
- Apply integrated PC or SIEMENS simotion controlling system, 15" touch screen.
- The electric control cabinet is equipped with independent temperature control system to ensure the normal operation of each control component.
- The equipment features swinging function, and the dual-support swinging function unit optimizes the performance of diamond wire-cut sapphire, shortens the cutting time, and improves the wafer quality.
- Minimal design number of pulleys (only 6 pulleys) to reduce wire distortion and fatigue.